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August 2011

## FDT86256

# N-Channel PowerTrench<sup>®</sup> MOSFET 150 V, 1.2 A, 845 m $\Omega$

#### **Features**

- Max  $r_{DS(on)}$  = 845 m $\Omega$  at  $V_{GS}$  = 10 V,  $I_D$  = 1.2 A
- Max  $r_{DS(on)} = 1280 \text{ m}\Omega$  at  $V_{GS} = 6.0 \text{ V}$ ,  $I_D = 1.0 \text{ A}$
- Very low Qg and Qgd compared to competing trench technologies
- Fast switching speed
- 100% UIL Tested
- RoHS Compliant

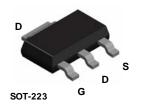


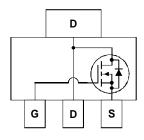
#### **General Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance and switching loss. G-S zener has been added to enhance ESD voltage level.

## **Applications**

- DC-DC conversion
- Inverter
- Synchronous Rectifier





## MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
$V_{DS}$	Drain to Source Voltage			150	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
	Drain Current -Continuous (Package limited)	T <sub>C</sub> = 25 °C		3	
	-Continuous (Silicon limited)	T <sub>C</sub> = 25 °C		2.5	^
ID	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	1.2	Α
	-Pulsed			2	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	1	mJ
D	Power Dissipation	T <sub>C</sub> = 25 °C		10	10/
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.3	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature F	Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	12	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	55	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
86256	FDT86256	SOT-223	13 "	12 mm	2500 units

## Electrical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

Symbol	Parameter Test Conditions		Min	Тур	Max	Units
Off Chara	acteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		100		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V			1	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	3.5	4	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-8		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 1.2 \text{ A}$		695	845	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 6 \text{ V}, I_D = 1.0 \text{ A}$		912	1280	mΩ
, ,		$V_{GS} = 10 \text{ V}, I_D = 1.2 \text{ A}, T_J = 125 \text{ °C}$		1298	1367	
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 1.2 \text{ A}$		0.3		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 75 V V 0 V	55	73	pF
Coss	Output Capacitance	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V, f = 1MHz	8	11	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 = 1101112	1	1.4	pF
$R_g$	Gate Resistance		1.3		Ω

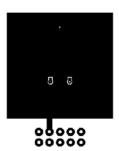
#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time				2.7	10	ns
t <sub>r</sub>	Rise Time		$V_{DD} = 75 \text{ V}, I_{D} = 1.2 \text{ A},$		1.7	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10 V, R <sub>GEN</sub>	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$		4.8	10	ns
t <sub>f</sub>	Fall Time				2.6	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V			1.2	2.0	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 6 \text{ V}$	V <sub>DD</sub> = 75 V,		0.8	1.0	
$Q_{gs}$	Gate to Source Charge		I <sub>D</sub> = 1.2 A		0.4		nC
$Q_{gd}$	Gate to Drain "Miller" Charge				0.3		nC

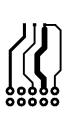
#### **Drain-Source Diode Characteristics**

$V_{SD}$	1Source to Drain Dioge Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 1.2 \text{ A}$ (N	lote 2)	0.9	1.3	V
		$V_{GS} = 0 \text{ V}, I_S = 1.0 \text{ A}$ (N	lote 2)	8.0	1.3	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 1.2 A, di/dt = 100 A/μs		47	75	ns
Q <sub>rr</sub>	Reverse Recovery Charge	11 <sub>F</sub> = 1.2 A, αι/αι = 100 A/μS		24	38	nC

1.  $R_{\theta,JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta,JC}$  is guaranteed by design while  $R_{\theta,CA}$  is determined by the user's board design.



a) 55 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b) 118 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0 %. 3. Starting T $_J$  = 25 °C, L = 3 mH, I $_{AS}$  = 1 A, V $_{DD}$  = 150 V, V $_{GS}$  = 10 V. 4. The diode connected between gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

### Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

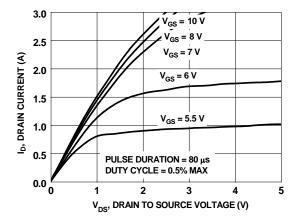


Figure 1. On-Region Characteristics

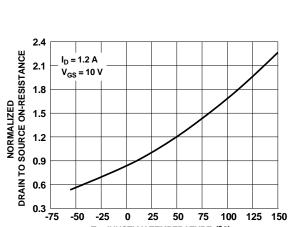


Figure 3. Normalized On-Resistance vs Junction Temperature

25 50 75 100

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

-50

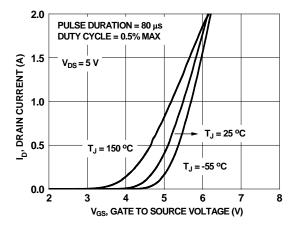


Figure 5. Transfer Characteristics

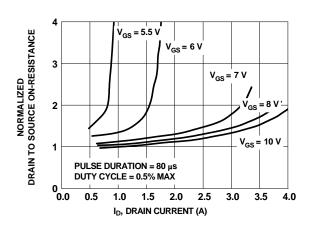


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

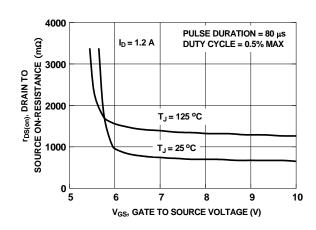


Figure 4. On-Resistance vs Gate to Source Voltage

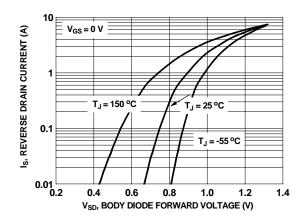


Figure 6. Source to Drain Diode **Forward Voltage vs Source Current** 

125 150

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

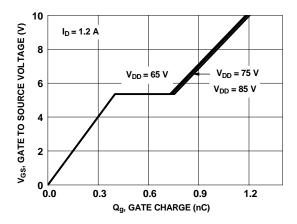


Figure 7. Gate Charge Characteristics

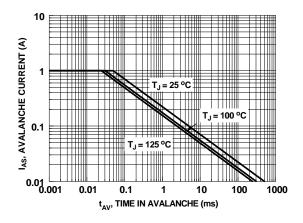


Figure 9. Unclamped Inductive Switching Capability

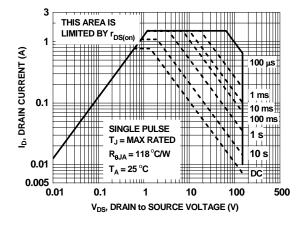


Figure 11. Forward Bias Safe Operating Area

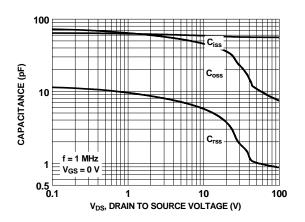


Figure 8. Capacitance vs Drain to Source Voltage

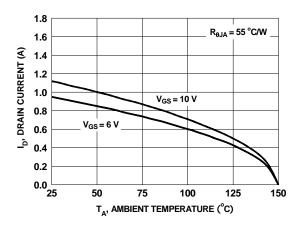


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

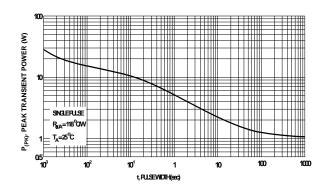


Figure 12. Single Pulse Maximum Power Dissipation

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

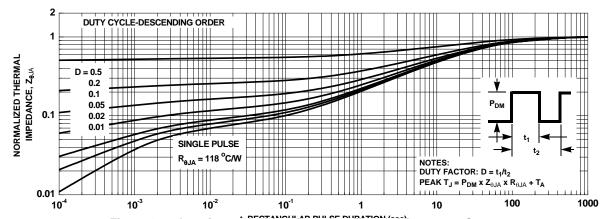
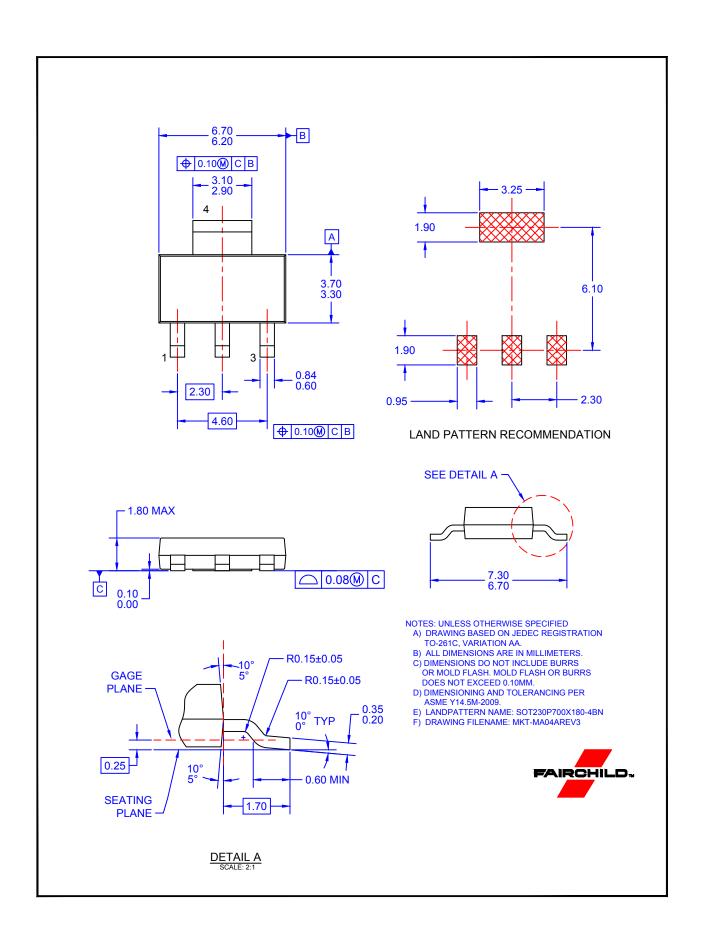


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



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